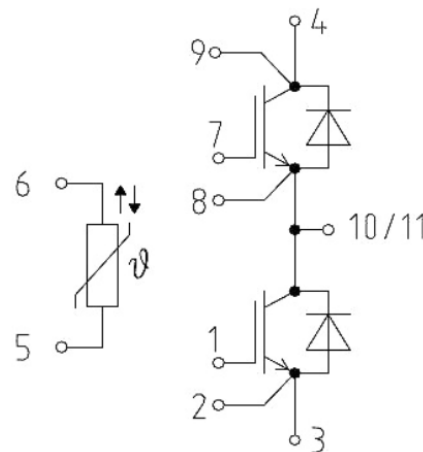


C5 series package: 1200V 300A IGBT module

Datasheet



Equivalent
Circuit Schematic

Features:

- Trenchgate Gen.7 IGBT technology
- $V_{CE(sat)}$ with positive temperature coefficient
- High RBSOA capability
- Low static losses: $V_{CE(sat)} = 1,5V@25^{\circ}C$
- Low dynamic losses

Options:

- Pre-applied TIM (option +M01)
- Adoption for parallel connection (V_f selection)

Typical Applications:

- Motor Drives
- Solar Applications
- UPS Systems
- Energy Stores

IGBT, Inverter / IGBT

Maximum Rated Values

Collector-emitter Voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	1200	V
Continuous DC Collector Current		I_{Cnom}	300	A
	$T_C = 100^{\circ}\text{C}, T_{vj\ max} \leq 175^{\circ}\text{C}$	I_C	358	A
Repetitive Peak Collector Current	$t_p = 1\text{ms}$	I_{CRM}	600	A
Gate-emitter Peak Voltage		V_{GES}	± 20	V

Characteristic Values

		min. typ. max.			
Collector-emitter Saturation Voltage ¹⁾	$I_C = 300\text{A}, V_{GE} = 15\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	V_{CEsat}	1.40 1.51 1.78 1.87	1.70	V
Gate Threshold Voltage	$V_{CE} = V_{GE}, I_C = 6\text{mA}, T_{vj} = 25^{\circ}\text{C}$	V_{GEth}	5.0	6.0	7.0 V
Gate Charge	$V_{GE} = 15\text{V/-8V}, V_{CE} = 600\text{V}$	Q_G	—	3.0	— μC
Internal Gate Resistor	$T_{vj} = 25^{\circ}\text{C}$	R_{Gint}	—	0.65	— Ω
Input Capacitance	$f = 100\text{kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$	C_{ies}	—	70.6	— nF
Reverse Transfer Capacitance	$f = 100\text{kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$	C_{res}	—	0.26	— nF
Collector-emitter Cutoff Current	$V_{CE} = 1200\text{V}, V_{GE} = 0\text{V}, T_{vj} = 25^{\circ}\text{C}$	I_{CES}	—	—	1 μA
Gate-emitter Leakage Current	$V_{CE} = 0\text{V}, V_{GE} = 20\text{V}, T_{vj} = 25^{\circ}\text{C}$	I_{GES}	—	—	500 nA
Turn-on Delay Time, Inductive Load	$I_C = 300\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = 15\text{V/-8V}$ $R_{GON} = 1.0\Omega$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	t_{don}	—	186 188 196 198	— ns
Rise Time, Inductive Load	$I_C = 300\text{A}, V_{CC} = 600\text{V}$ $V_{GE} = 15\text{V/-8V}$ $R_{GON} = 1.0\Omega$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	t_r	—	40 50 52 65	— ns
Turn-off Delay Time, Inductive Load	$I_C = 300\text{A}, V_{CC} = 600\text{V}$ $V_{GE} = -8\text{V/15V}$ $R_{GON} = 1.0\Omega$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	t_{doff}	—	351 397 407 428	— ns
Fall Time, Inductive Load	$I_C = 300\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = -8\text{V/15V}$ $R_{Goff} = 1\Omega$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	t_f	—	119 181 209 210	— ns
Turn-on Energy Loss per Pulse	$I_C = 300\text{A}, V_{CC} = 600\text{V}, L_{\sigma} = 35\text{nH}$ $V_{GE} = -8\text{V/15V}, R_{GON} = 1.0\Omega$ $di/dt = 3600\text{A}/\mu\text{s} (T_{vj} = 175^{\circ}\text{C})$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	E_{on}	—	11.6 17.0 18.8 21.7	— mJ
Turn-off energy Loss per Pulse	$I_C = 300\text{A}, V_{CC} = 600\text{V}, L_{\sigma} = 35\text{nH}$ $V_{GE} = 15\text{V/-8V}, R_{GON} = 1.0\Omega$ $du/dt = 7100\text{V}/\mu\text{s} (T_{vj} = 175^{\circ}\text{C})$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	E_{off}	—	20.1 28.6 31.1 36.0	— mJ
SC Data	$V_{CC} = 600\text{V}$ $V_{GE} = 15\text{V/-8V}$ $t_p \leq 10\mu\text{s}, T_{vj} = 150^{\circ}\text{C}$ $t_p \leq 8\mu\text{s}, T_{vj} = 175^{\circ}\text{C}$	I_{sc}	—	1600 1500	— A

Thermal Resistance, Junction to Case	Per IGBT	R_{thJC}	—	0.104	—	K/W
Thermal Resistance, Case to Heatsink	Per IGBT $\lambda_{grease} = 1W/(m \cdot K)$	R_{thCH}	—	0.023	—	K/W
Temperature under Switching Conditions		$T_{vj\ op}$	-40		175	°C

Diode, Inverter Maximum Rated Values

Repetitive Peak Reverse Voltage	$T_{vj} = 25^{\circ}C$	V_{RRM}	1200	V
Continuous DC Forward Current		I_{Fnom}	300	A
Repetitive Peak Forward Current	$t_p = 1ms$	I_{FRM}	600	A

Characteristic Values

			min. typ. max.			
Forward Voltage ¹⁾	$I_F = 300A, V_{GE} = 0V$	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	V_F	1.50 1.92 1.94 1.87	2.40	V
Peak Reverse Recovery Current	$I_F = 300A, V_{CC} = 600V$ $V_{GE} = -8V$ $-di_F/dt = 3600A/\mu s$ ($T_{vj} = 175^{\circ}C$)	$T_{vj} = 25^{\circ}C$ $T_{vj} = 125^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	I_{RM}	— 248 276 284 292	—	A
Recovery Charge	$I_F = 300A, V_{CC} = 600V$ $V_{GE} = -8V$ $-di_F/dt = 3600A/\mu s$ ($T_{vj} = 175^{\circ}C$)	$T_{vj} = 25^{\circ}C$ $T_{vj} = 125^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	Q_R	— 16.5 28.5 32.6 37.6	—	μC
Reverse Recovery Energy	$I_F = 300A, V_{CC} = 600V$ $V_{GE} = -8V$ $-di_F/dt = 3600A/\mu s$ ($T_{vj} = 175^{\circ}C$)	$T_{vj} = 25^{\circ}C$ $T_{vj} = 125^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	E_{rec}	— 9.0 16.7 19.0 25.4	—	mJ
Thermal Resistance, Junction to Case	Per FRD		R_{thJC}	—	0.160	K/W
Thermal Resistance, Case to Heatsink	Per FRD $\lambda_{grease} = 1W/(m \cdot K)$		R_{thHC}	—	0.026	K/W
Temperature under Switching Conditions			$T_{vj\ op}$	-40	—	175 °C

NTC-Thermistor / NTC

Maximum Rated Values

			min.	typ.	max.	
Rated Resistance	T _{NTC} = 25°C	R ₂₅	—	5	—	kΩ
Deviation of R100 R100	T _{NTC} = 100°C, R ₁₀₀ = 465Ω	ΔR/R	-7.3	—	7.3	%
Power Dissipation	T _{NTC} = 25°C	P ₂₅	—	—	10	mW
B-Value B	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298.15K))]$	B _{25/50}	—	3380	—	K
	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298.15K))]$	B _{25/80}	—	3470	—	K
	$R_2 = R_{25} \exp[B_{25/100}(1/T_2 - 1/(298.15K))]$	B _{25/100}	—	3520	—	K

Module

Isolation Test Voltage	RMS, f=50Hz, t = 1min	VISOL	2.5	kV
Material of Module Baseplate			Cu	
Internal Isolation			Al ₂ O ₃	
Creepage Distance	Terminal to heatsink, min Terminal to terminal, min		15.0 13.0	mm
Clearance	Terminal to heatsink, min Terminal to terminal, min		12.5 10.0	mm
Comparative Tracking Index		CTI	200 ²⁾	

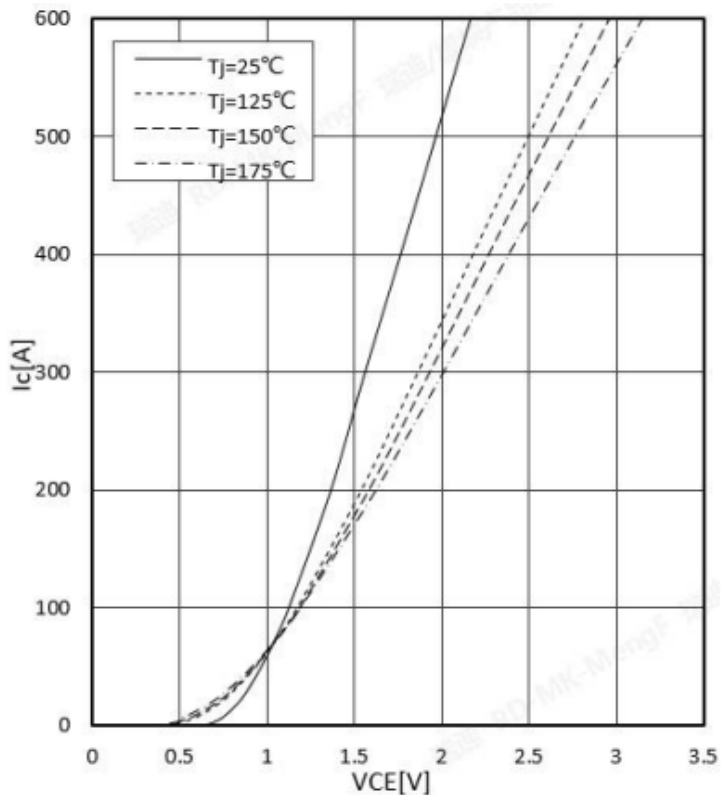
			min.	typ.	max.	
Stray Inductance Module		L _{sCE}	—	17	—	nH
Module Lead Resistance, Terminals-Chip	T _C = 25°C, Per Switch	R _{CC'+EE'}	—	0.8	—	mΩ
Storage Temperature		T _{stg}	-40	—	125	°C
Mounting Torque for Module Mounting	Screw M5 / M5	M	3.0	—	6.0	Nm
Power Terminal Installation Torque	Screw M6 / M6	M	3.0	—	6.0	Nm
Weight		G	—	345	—	g

1) Terminal impedance is not included.

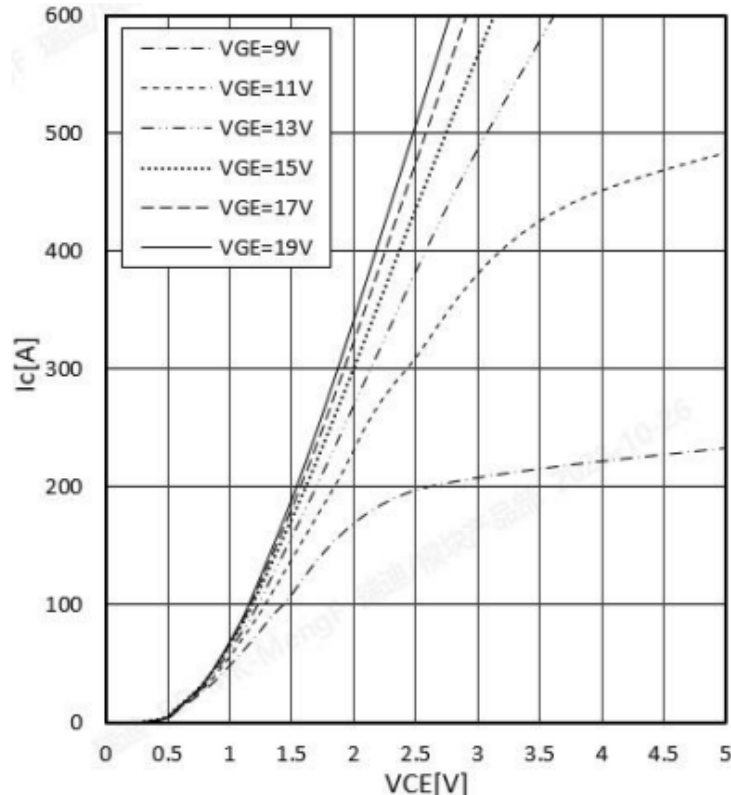
2) CTI is about 200.

Circuit Diagram

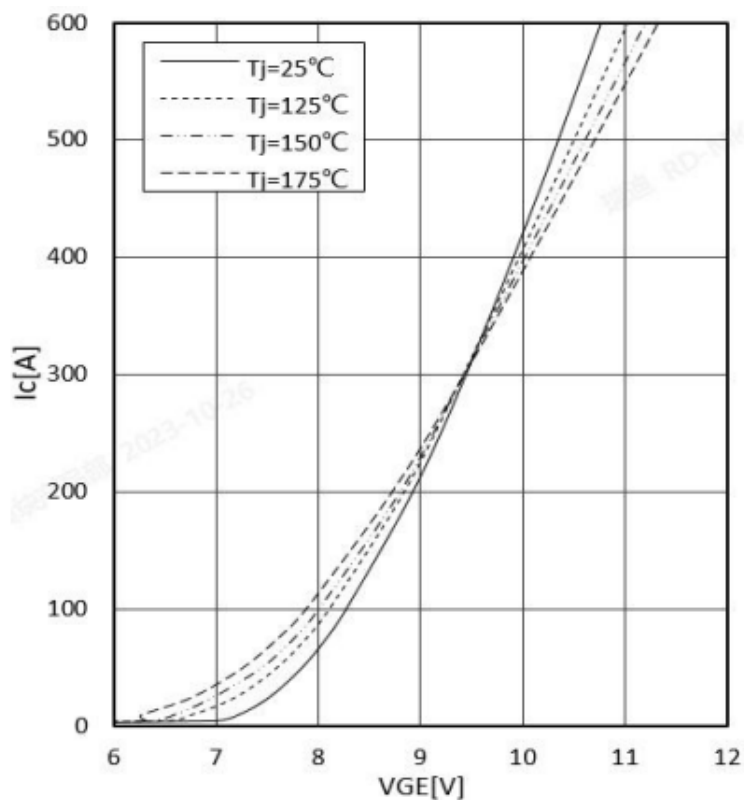
Output characteristic IGBT, Inverter (typical), IGBT
 $I_c = f(V_{CE})$, $V_{GE} = 15V$



Output characteristic IGBT, Inverter (typical), IGBT
 $I_c = f(V_{CE})$, $T_{vj} = 175^{\circ}C$

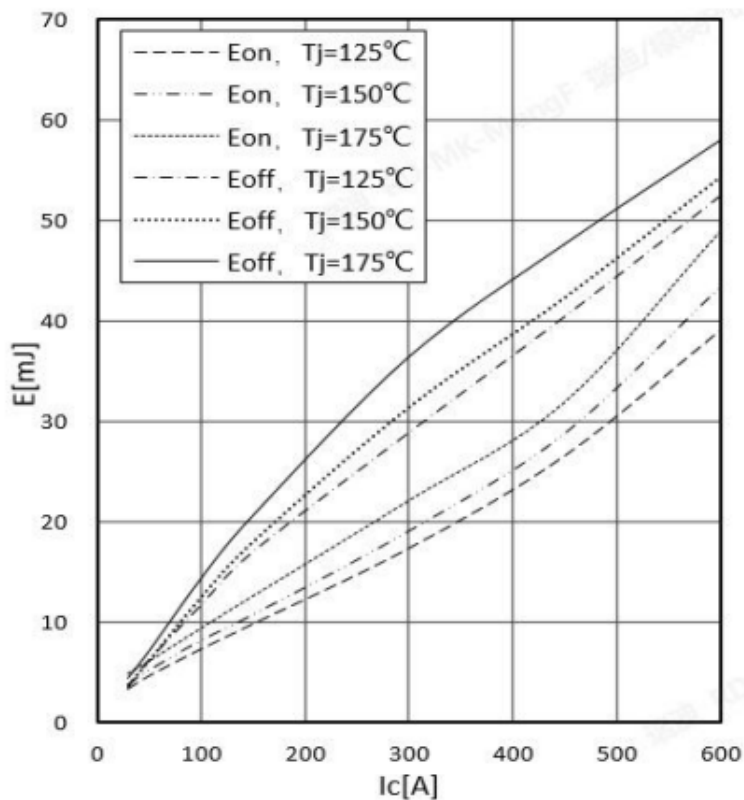


Transfer characteristic IGBT, Inverter (typical), IGBT
 $I_c = f(V_{GE})$, $V_{CE} = 20V$

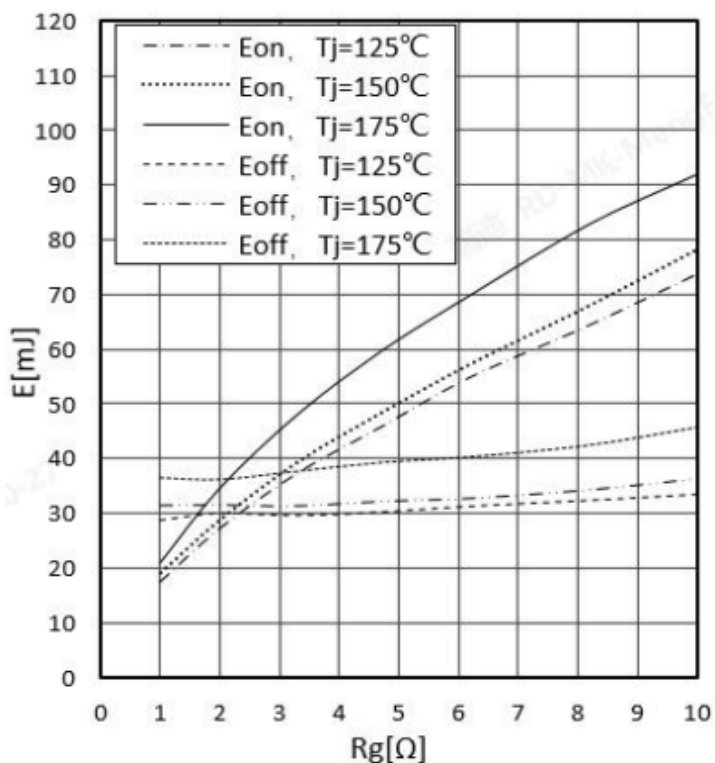


Switching losses IGBT, Inverter (Typical), IGBT

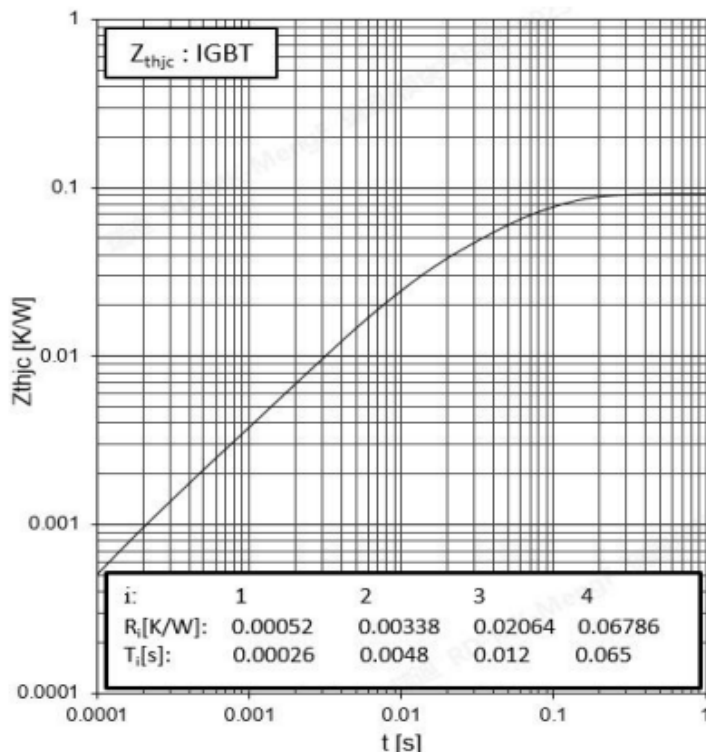
$E_{on} = f(I_c)$, $E_{off} = f(I_c)$
 $V_{GE} = +15V/-8V$, $R_{Gon} = 1\Omega$, $R_{Goff} = 1\Omega$, $V_{CC} = 600V$



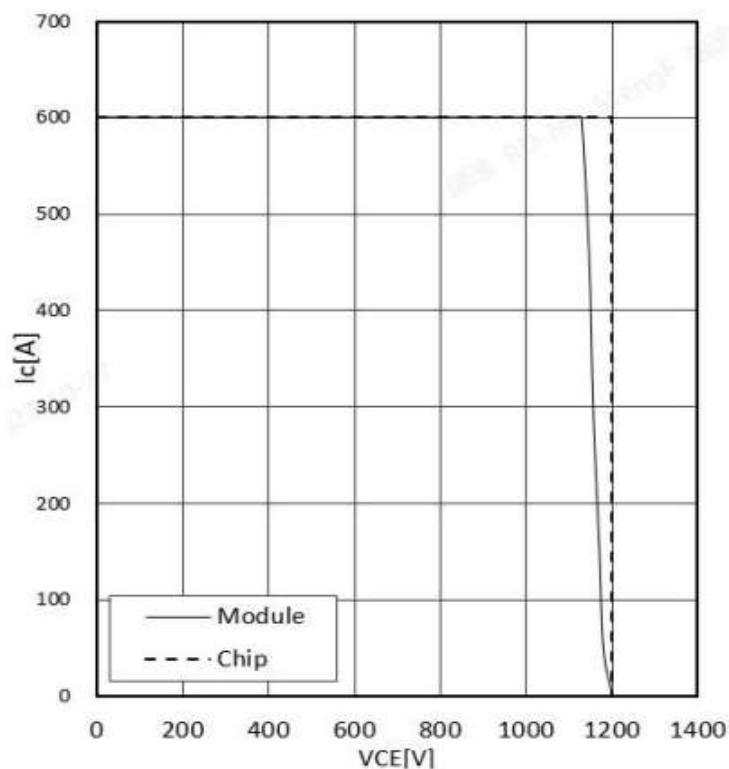
Switching losses IGBT, Inverter (Typical), IGBT
 $E_{on} = f(R_g)1\Omega$, $E_{off} = f(R_g)$,
 $V_{GE} = +15V/-8V$, $I_c = 300A$, $V_{CC} = 600V$



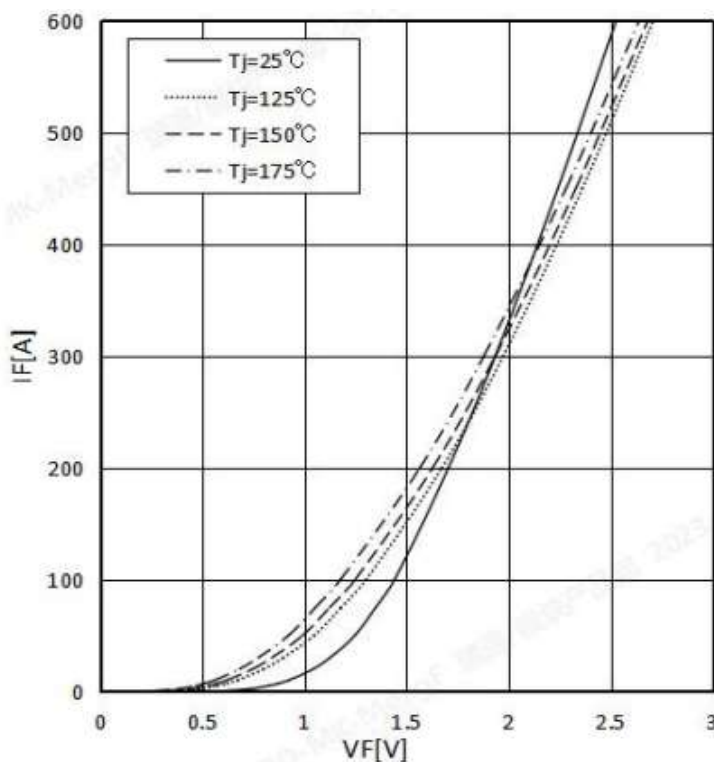
Transient thermal impedance IGBT, Inverter
 $Z_{thjc} = f(t)$



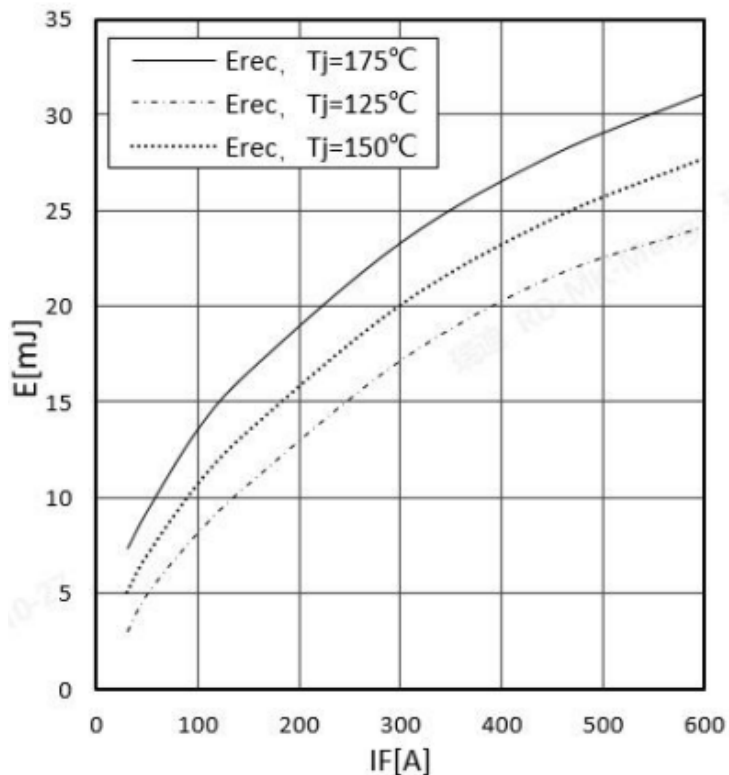
Reverse bias safe operating area IGBT, Inverter (RBSOA)
 $I_c = f(V_{CE})$
 $V_{GE} = +15V/-8V$, $R_{goff} = 1\Omega$, $T_{vj} = 175^\circ\text{C}$



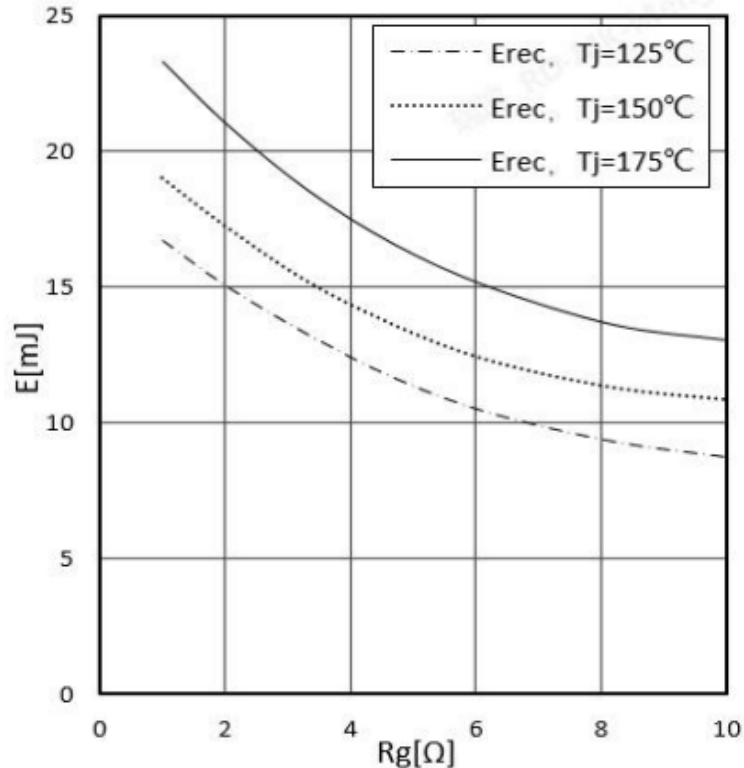
Forward characteristic of Diode, Inverter (typical)
 $I_F = f(V_F)$



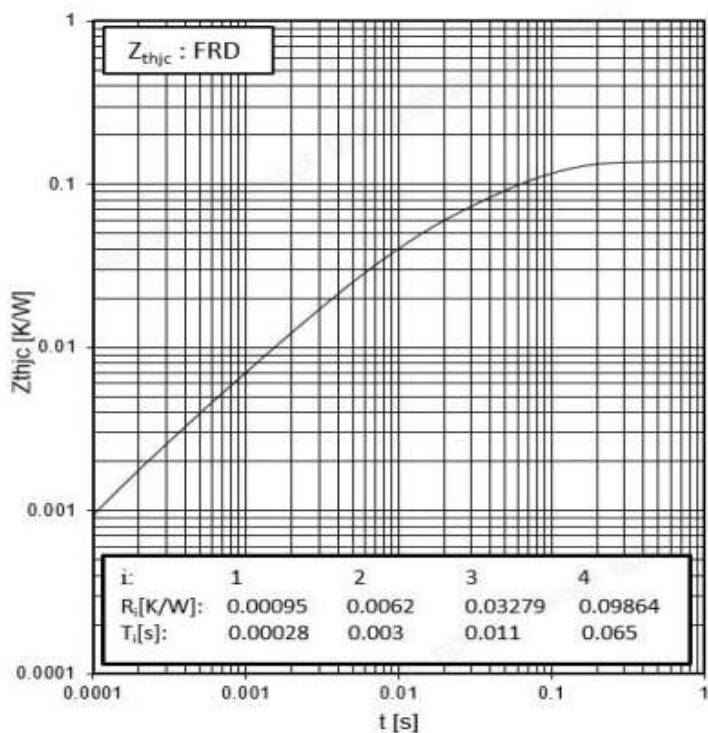
Switching losses Diode, Inverter (typical)
 $E_{rec} = f(I_F)$, $R_{gon} = 0.5\Omega$, $V_{CE} = 600V$



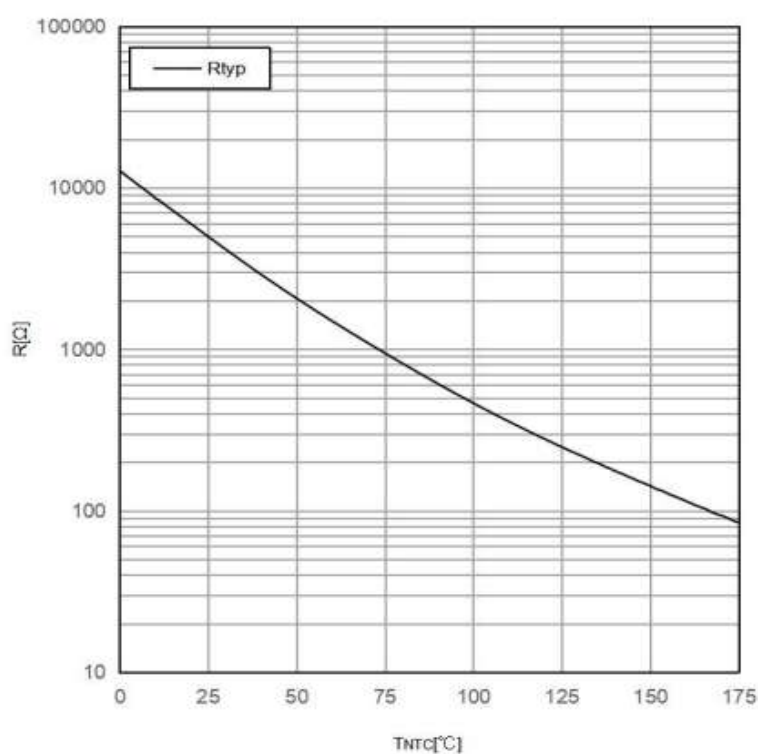
Switching losses Diode, Inverter (typical)
 $E_{rec} = f(R_g)$, $I_F = 450A$, $V_{CE} = 600V$



Transient thermal impedance IGBT, Inverter
 $Z_{thJC} = f(t)$

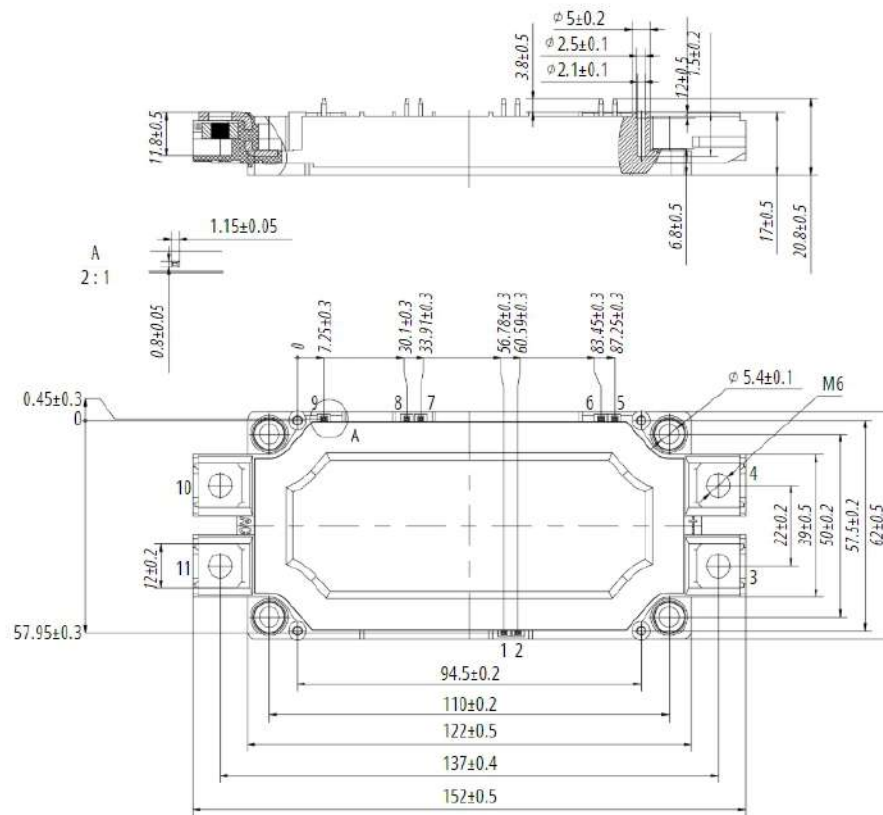


NTC-Thermistor-temperature characteristic (typical)
 $R = f(t)$

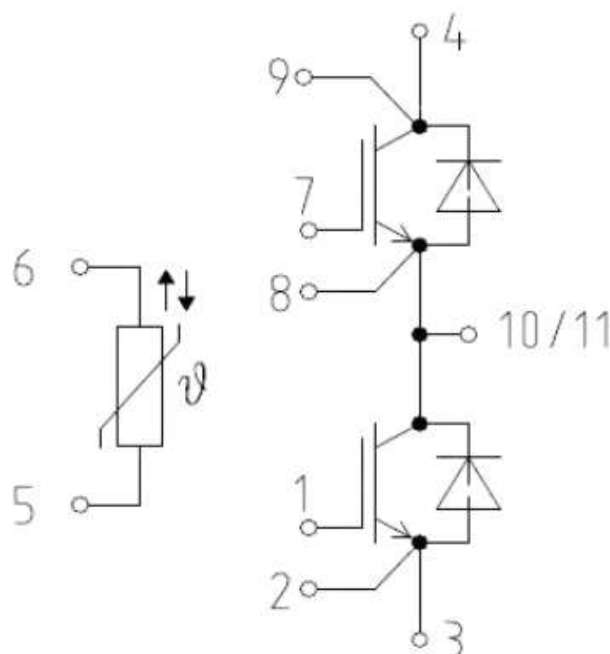


Package Dimension

Dimensions in Millimeters



Internal Circuit



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